

高回弹导热垫片

High Rebound Thermal Pad

产品介绍

PRODUCT INTRODUCTION

高回弹导热垫片是指有机硅树脂利用特殊的配方及工艺制成的具有高导热性能、高回弹的特殊界面填充材料。在相对较低的压力下便可以实现低界面热阻性能,应用于发热功率器件与散热器或机壳间,可以有效排除空气,降低空气的接触热阻,达到有效的填充效果,并且高强度,不易破损。

High rebound thermal pad is a silicone-based thermal interface material with high thermal conductivity and low compression set.

Low interface thermal resistance can be achieved at relatively low compression force. It was applied between heat source and heatsink/casing to reduce the contact thermal resistance by replacing air. High strength and rebound provides super reliability avoiding of crack and pump-out.

产品特点

PRODUCT FEATURE

- 良好的导热率,低热阻
- 材料柔软,低应力,良好的填充效果,对元器件无损伤
- 高强度、高回弹性、可靠性佳
- Good thermal conductivity and low thermal resistance
- Soft, low stress, good filling effect and no damage to components
- High strength, high rebound, and super reliability

典型应用

TYPICAL APPLICATION

- 电子通讯设备
- 平板显示器
- 车用电子产品
- 新能源汽车
- Telecomm equipment
- Flat panel displays
- Automotive electronics
- New energy vehicles

产品参数

PRODUCT PARAMETER

产品型号 Product Name	厚度 Thickness	导热系数 Thermal Conductivity	密度 Density	硬度 Hardness	回弹率 Compression Resilience Ratio	介电常数 Dielectric Constant	体积电阻率 Volume Resistivity	使用温度 Application Temperature	阻燃等级 Flammability Rating	保质期 Shelf Life
	mm	W/m.K	g/cm ³	Shore 00	%	@1MHz	Ω·cm	℃	UL-94	month
STP 150 HR	0.5~10.0	1.5	2.60	30	90	4	1*10 ¹³	-40 ~ 150	V-0	24
STP 300 HR	0.5~10.0	2.7	2.90	40	90	4.54	1*10 ¹³	-40 ~ 150	V-0	24
STP 301 HR	0.5~10.0	2.7	2.90	60	90	4.34	1*10 ¹²	-40 ~ 200	V-0	24